CT2-RX/TX IC

Description

The IC for digital cordless telephone application is fabricated using TEMIC's most advanced UHF process. It covers the CT2 band (864 MHz to 868 MHz) as well as the CT2 Plus band (up to 952 MHz). The RX/TX circuit provides the down conversion to the data stream and the up conversion from the first IF. In conjunction with TEMIC's RF front end, Twin PLL, I/Q modulator and

Features

- Low supply voltage 2.9 V typical (min. 2.7 V)
- Provides down conversion to the data stream, up conversion from the first IF
- Integrated UHF and VHF VCOs
- Low noise figure of RX path (NF $\leq 10 \text{ dB}$)
- RX and TX power down
- First IF filter used for transmit as well receive mode
- Temperature compensated logarithmic Receiver Signal Strength Indicator (RSSI) with a 75 dB dynamic range

Block Diagram (Simplified Schematic)

- Low power consumption in RX and TX mode (<20 mA typ.)
- SSO28 plastic package

AMDs CT2 PhoXTM controller AM 79C4xx a complete CT2 IC kit is available.

Electrostatic sensitive device. Observe precautions for handling.



Benefits

- Low power consumption results in extended talk time
- Few external components and very small package save space



Rev. A3, 05-Oct-98

Ordering Information

Extended Type Number	Package	Remarks
U2760B-AFS	SSO28	Rail, MOQ 600pcs.
U2760B-AFS G3	SSO28	Tape + reel, MOQ 4000 pcs.

Functional Description

MX1

Mixer 1 converts the RF signal to the first IF. It has a high impedance, unsymmetrical input and a symmetrical open collector output.

MX2

The second mixer provides the down conversion to the second IF. An external SAW filter is placed at its input to provide rejection of the image frequency and spurious signals that went through the RF filtering.

LIMITER / RSSI

This block contains a high gain (100 dB) amplifier, providing a limited signal at the second IF frequency for the demodulation, as well as a signal strength indicator providing an output voltage proportional to the input power.

Demod

The quadrature demodulator in the receiving path contains an internal 10 pF quadrature capacitor to couple the IF signal to the external Tank providing the 90 degree phase shift. An external bit slicer reshapes the bits, a sample and hold circuit maintains the average DC value at the demodulator when switching the signal between transmission and reception.

COMP

The comparator circuit with 100 k Ω input resistor and external input biasing has a 10 mV hysteresis. It is designed to square up the demodulated data signal.

MX3

The third mixer converts the 800 kHz signal coming from the modulator circuit to the IF frequency. It has a high impedance, unsymmetrical input and a symmetrical open collector output.

MX4

This mixer is designed for the up conversion of the RF frequency. It has a high impedance, unsymmetrical input and a symmetrical open collector output. The image rejection is obtained by external RF filtering.

The same first IF filter is used for the transmit path and the receive path. In the transmit path, this filter is supposed to eliminate the mixing products from MX3, in particular, the harmonics of the IF frequency.

VCO1

The UHF VCO covers the frequency band up to 700 MHz. For external VCO application this circuit can be used as a buffer stage.

VCO2

This VCO covers a frequency band up to 400 MHz.

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Pin Description



Figure 2. Pinning

1MX2/4inMixer2/ Mixer4 input2MX2/4ninMixer2/ Mixer4 ref. inp3MX3inMixer3 input4LIMITinLimiter/RSSI input5VCO1outVCO1 output (to PLL)6VCO1tankVCO1 resonator7VCO1refVCO1 resonator, to be8GNDvco/lfGround VCO, low freq parts9VCCvco/lfPower supply VCO/LF10RXdataRX data output	blocked uency
3MX3inMixer3 input4LIMITinLimiter/RSSI input5VCO1outVCO1 output (to PLL)6VCO1tankVCO1 resonator7VCO1refVCO1 resonator, to be8GNDvco/lfGround VCO, low freq parts9VCCvco/lfPower supply VCO/LF10RXdataRX data output	blocked uency
4 LIMITin Limiter/RSSI input 5 VCO1out VCO1 output (to PLL) 6 VCO1tank VCO1 resonator 7 VCO1ref VCO1 resonator, to be 8 GNDvco/lf Ground VCO, low freq parts 9 VCCvco/lf Power supply VCO/LF 10 RXdata RX data output	uency
5 VCO1out VCO1 output (to PLL) 6 VCO1tank VCO1 resonator 7 VCO1ref VCO1 resonator, to be 8 GNDvco/lf Ground VCO, low freq parts 9 VCCvco/lf Power supply VCO/LF 10 RXdata RX data output	uency
6 VCO1tank VCO1 resonator 7 VCO1ref VCO1 resonator, to be 8 GNDvco/lf Ground VCO, low freq parts 9 VCCvco/lf Power supply VCO/LF 10 RXdata RX data output	uency
7 VCO1ref VCO1 resonator, to be 8 GNDvco/lf Ground VCO, low freq parts 9 VCCvco/lf Power supply VCO/LF 10 RXdata RX data output	uency
8 GNDvco/lf Ground VCO, low freq parts 9 VCCvco/lf Power supply VCO/LF 10 RXdata RX data output	uency
parts 9 VCCvco/lf 10 RXdata	. •
10 RXdata RX data output	parts
-	T
11 QUAD Quadrature filter	
12 DEMODout Demodulator output	
13 COMPin Comparator input	
14 COMPcap Comparator blocking c	apacitor
15 RXenable RX enable	
16 VCO2out VCO2 output (to PLL)	
17 VCO2ref VCO2 resonator, to be	blocked
18 VCO2tank VCO2 resonator	
19 GND Ground	
20 VCC Power supply voltage	
21 MX1in Mixer1 input	
22MX4outnMixer 4 output n	
23MX4outpMixer 4 output p	
24 TXenable TX enable	
25 MX1/3outn Mixer1/ Mixer3 output	n
26 MX1/3outp Mixer1/Mixer3 output	р
27 RSSIout Signal strength output	
28 MX2out Mixer2 output	

Pin Functions

Pin	Symbol	Pin Voltage	Function	Equivalent Circuit
1	MX2/4in	1.5	Mixer2/ Mixer4 input	
2	MX2/4nin	1.5	Mixer2/ Mixer4 complementary input Pin 1 is the input of the mixers, Pin 2 can be used for differential input signal, or should be connected to GND via a bypass capacitor	$\begin{array}{c} \begin{array}{c} \\ 1 \\ \end{array} \\ \hline \\ \end{array} \\ \\ \end{array} \\ \hline \\ \end{array} \\ \\ \\ \end{array} \\ \\ \\ \end{array} \\ \\ \\ \\ \end{array} \\$
3	MX3in	1.7 (RX) 2.4 (TX)	Mixer3 input complementary input is internally connected to GND via a bypass capacitor	To MX3
4	LIMITin	2.1	Limiter/RSSI input	Vcc-
11	QUAD	1.5	Quadrature filter	(4)
12	DEMODout	1.2	Demodulator output	
5	VCO1out	1.1	VCO1 output (to PLL)	9
6	VCO1tank	1.5	VCO1 resonator	
7	VCO1ref	1.5	VCO1 reference, to be blocked. This Pin is also internally connected to GND via a bypass capacitor	
8	GNDvco/lf	_	Ground VCO, low frequency parts	
9	VCCvco/lf	_	Power supply VCO/LF parts	



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Pin	Symbol	Pin Voltage	Function	Equivalent Circuit
10	RXdata	0 to 2.9	RX data output	Vcc T 50k
13	COMPin	1.2	Comparator input	
14	COMPcap	1.2	Comparator blocking capacitor	
15	RXenable	_	RX enable	Vcc (15)
16	VCO2out	1.1	VCO2 output (to PLL)	
17	VCO2ref	1.6	VCO2 resonator, to be blocked	
18	VCO2tank	1.6	VCO2 resonator	
19	GND	-	Ground (mixer parts)	
20	VCC	_	Power supply (mixer parts)	
21	MX1in	1.5	Mixer1 input complimentary input is internally connected to GND via a bypass capacitor	
22	MX4outn	_	Mixer 4 output n	
23	MX4outp	_	Mixer 4 output p	LO1

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Pin	Symbol	Pin Voltage	Function	Equivalent Circuit
24	TXenable	_	TX enable	(24) (24) (24) (24)
25	MX1/3outn	_	Mixer1/ Mixer3 output n	
26	MX1/3outp	_	Mixer1/ Mixer3 output p	from from MX1 in MX3 in
27	RSSIout	0.2 to 2.7	Signal strength output	Vcc $Vcc2725k$
28	MX2out	1.0 (RX) 2.4 (TX)	Mixer2 output	

Absolute Maximum Ratings

Parameters	Symbol	Value	Unit
Supply voltage	V _{CC}	0 to +5	V
Input voltages Pins 1, 2, 3, 4, 13, 14, 15, 21 and 24	V _{in}	0 to V _{CC}	V
Input voltages Pins 6, 7, 17 and 18	V _{in}	1.5	V
Junction temperature	Tj	125	°C
Storage temperature range	T _{stg}	-40 to +125	°C

Thermal Resistance

Parameters	Symbol	Value	Unit
Junction ambient SSO28	R _{thJA}	130	K/W

Operating Conditions

Parameters	Symbol	Value	Unit
Supply voltage	V _{CC}	2.7 to 3.6	V
Operating temperature	T _{amb}	-5 to +45	°C

Electrical Characteristics: Receiver Input Mixer (MX1)

Test conditions (unless otherwise specified): $V_{CC} = 2.9$ V, $T_{amb} = 25$ °C, referred to application circuit, fRF = 866.05 MHz, fIF1 = 240.05 MHz.

Parameters	Test Conditions / Pins	Symbol	Min.	Тур.	Max.	Unit
Supply voltage range	Pin 20	V _{CC}	2.7	2.9	3.6	V
Supply current	$@V_{CC} = 2.9 V$, Pin 20	Is		3		mA
Input impedance	Pin 21	Zin		3		kΩ
Input frequency	Pin 21	fin			1000	MHz
Output frequency	Pins 25 and 26	fout		240	300	MHz
Power gain	Pins 21, 25 and 26	Gp		8		dB
Noise figure	Pins 21, 25 and 26	NF		8	10	dB
Compression	Pins 21, 25 and 26	P_1dB	-18			dBm
Third order input intercept point	Pins 21, 25 and 26	IIP3	-8			dBm
LO to RF isolation	Pin 21	Isollo	20			dB
LO \pm (IF/2) response	@ Pin = -84 dBm, Pin 21				-10	dB

Electrical Characteristics: Receiver IF Mixer (MX2)

Test conditions (unless otherwise specified): $V_{CC} = 2.9$ V, $T_{amb} = 25^{\circ}$ C, referred to application circuit, fIF1 = 240.05 MHz, fIF2 = 800 kHz.

Parameters	Test Conditions / Pins	Symbol	Min.	Тур.	Max.	Unit
Supply voltage range	Pin 20	V _{CC}	2.7	2.9	3.6	V
Supply current	@ V _{CC} = 2.9 V, Pin 20	Is		3		mA
Input impedance	Pin 1	Zin	130	200	300	Ω
Input frequency	Pin 1	fin			300	MHz
Output frequency	Pin 28	fout		0.8	15	MHz
Power gain	Pins 1 and 28	Gp	10	11		dB
Noise figure	Pins 1 and 28	NF			20	dB
Compression	Pins 1 and 28	P_1dB	-20			dBm
Third order input intercept point	Pins 1 and 28	IIP3	-10			dBm
LO to RF isolation	Pin 1	Isollo	20			dB
LO \pm (IF/2) response	@ Pin = -40 dBm, Pin 1				-35	dB

Electrical Characteristics: RSSI/Limiter Amplifier

Test conditions (unless otherwise specified): $V_{CC} = 2.9$ V, $T_{amb} = 25$ °C, referred to application circuit, fLIMIT = 800 kHz.

Parameters	Test Conditions / Pins	Symbol	Min.	Тур.	Max.	Unit
Supply voltage range	Pin 9	V _{CC}	2.7	2.9	3.6	V
Supply current	@ Vcc = 2.9 V, Pin 9	Is		1.5		mA
Input impedance	Pin 4	Zin		1500		Ω
Voltage gain	Pin 4	Gv		100		dB
Frequency range	Pin 4	f LIMIT	0.5	0.8	5	MHz
RSSI range	Pins 4 and 27		- 90		- 15	dBm
RSSI voltage at Pmin	Pins 4 and 27		0.2		0.4	V
RSSI voltage at Pmax	Pins 4 and 27		2.4		2.6	V
RSSI accuracy	Pins 4 and 27		- 2		2	dB
Output impedance	Pins 27	Rrssi	19	24	29	kΩ
Rise time	CRSSI = 1 nF, $Pin 27$				50	μs
Fall time	CRSSI = 1 nF, $Pin 27$				50	μs

Electrical Characteristics: Demodulator

Test conditions (unless otherwise specified): $V_{CC} = 2.9$ V, $T_{amb} = 25$ °C, referred to application circuit, fLIMIT = 800 kHz.

Parameters	Test Conditions / Pins	Symbol	Min.	Тур.	Max.	Unit
Supply voltage range	Pin 9	V _{CC}	2.7	2.9	3.6	V
Supply current	@ Vcc = 2.9 V, Pin 9	Is		0.2		mA
Output voltage	±18 kHz deviation,	Vout		120		mV _{rms}
	Pins 4 and 12					

Electrical Characteristics: Comparator

Test conditions (unless otherwise specified): $V_{CC} = 2.9 \text{ V}$, $T_{amb} = 25^{\circ}\text{C}$, referred to application circuit	

Parameters	Test Conditions / Pins	Symbol	Min.	Тур.	Max.	Unit
Supply voltage range	Pin 9	Vcc	2.7	2.9	3.6	V
Supply current	@ Vcc = 2.9 V, Pin 9	Is		0.15		mA
Input hysteresis	Pins 13 and 14			10		mV
Output HIGH voltage	RLoad to GND $\geq 500 \text{ k}\Omega$, Pin 10		2.3			V
Output LOW voltage	RLoad to $V_{CC} \ge 50 \text{ k}\Omega$, Pin 10				0.6	V

Electrical Characteristics Transmitter IF Mixer (MX3)

Test conditions (unless otherwise specified): $V_{CC} = 2.9$ V, $T_{amb} = 25$ °C, referred to application circuit, fin = 800 kHz, fIF = 240.05 MHz.

Parameters	Test Conditions / Pins	Symbol	Min.	Тур.	Max.	Unit
Supply voltage range	Pin 20	V _{CC}	2.7	2.9	3.6	V
Supply current	@ V _{CC} = 2.9 V, Pin 20	Is		1.3		mA
Input impedance	Pin 2	Zin		5		kΩ
Input frequency	Pin 3	fin		0.8	15	MHz
Output frequency	Pins 25 and 26	fout		250	300	MHz
Output power	$v_{inpp} = 320 \text{ mV}$ Pins 25 and 26	Pout		- 16		dBm
Noise figure	Pins 2, 25 and 26	NF			25	dB

Electrical Characteristics Transmitter Output Mixer (MX4)

Test conditions (unless otherwise specified): $V_{CC} = 2.9$ V, $T_{amb} = 25$ °C, referred to application circuit, fIF = 240.05 MHz, fRF = 866.05 MHz.

Parameters	Test Conditions / Pins	Symbol	Min.	Тур.	Max.	Unit
Supply voltage range	Pin 20	Vcc	2.7	2.9	3.6	V
Supply current	@ V _{CC} = 2.9 V, Pin 20	Is		3.5	4	mA
Input impedance	Pin 1	Zin	130	200	300	Ω
Input frequency	Pin 1				300	MHz
Output frequency	Pins 22 and 23				900	MHz
Output power	$P_{In} = -22 \text{ dBm},$ Pins 22 and 23	Pout	-16	- 14		dBm
Noise figure	Pins 1, 22 and 23	NF			12	dB
LO leakage	Pins 22 and 23	Lklo			-34	dBm
IF leakage	Pins 22 and 23	Lkif			-45	dBm
(2*IF) leakage	Pins 22 and 23	Lk2IF			- 55	dBm
(3*IF) leakage	Pins 22 and 23	Lk3IF			- 65	dBm
(n*IF) leakage, $n > 3$	Pins 22 and 23	LknIF			- 60	dBm

Electrical Characteristics: UHF Voltage Controlled Oscillator (VCO1)

Test conditions (unless otherwise specified): $V_{CC} = 2.9 \text{ V}$, $T_{amb} = 25^{\circ}C$, referred to application circuit, f = 626 MHz

Parameters	Test Conditions / Pins	Symbol	Min	Тур	Max	Unit
Supply voltage range	Pin 9	V _{CC}	2.7	2.9	3.6	V
Supply current	@ Vcc = 2.9 V, Pin 9	Is		3		mA
Frequency bandwidth	Pins 5, 6 and 7	fBw			700	MHz
Phase noise ±100 kHz	Pins 5, 6 and 7	Pn			- 86	dBc/Hz
Phase noise ±200 kHz	Pins 5, 6 and 7	Pn			- 104	dBc/Hz
Phase noise ±300 kHz	Pins 5, 6 and 7	Pn			- 109	dBc/Hz
Phase noise ±400 kHz	Pins 5, 6 and 7	PN			- 125	dBc/Hz
Phase noise @ 50 MHz	Pins 5, 6 and 7	Pn			- 150	dBc/Hz
Output power	50Ω termination, Pin 5	Pout	- 15			dBm

Electrical Characteristics: VHF Voltage Controlled Oscillator (VCO2)

Test conditions (unless otherwise specified): $V_{CC} = 2.9 \text{ V}$, $T_{amb} = 25^{\circ}C$, referred to application circuit, f = 239.25 MHz

Parameters	Test Conditions / Pins	Symbol	Min	Тур	Max	Unit
Supply voltage range	Pin 9	Vcc	2.7	2.9	3.6	V
Supply current	@ Vcc = 2.9 V, Pin 9	Is		2.5		mA
Frequency bandwidth	Pins 16, 17 and 18	fBw			400	MHz
Phase noise 100 kHz	Pins 16, 17 and 18	PN			- 86	dBc/Hz
Phase noise 200 kHz	Pins 16, 17 and 18	PN			- 114	dBc/Hz
Phase noise 300 kHz	Pins 16, 17 and 18	PN			- 119	dBc/Hz
Phase noise 400 kHz	Pins 16, 17 and 18	PN			- 135	dBc/Hz
Phase noise @ 50 MHz	Pins 16, 17 and 18	PN			- 150	dBc/Hz
Output power	50 Ω termination, Pin 16	Pout	- 15			dBm



Applications Information



Figure 3.

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Application Circuit



Figure 4.



Package Information



Ozone Depleting Substances Policy Statement

It is the policy of **TEMIC Semiconductor GmbH** to

- 1. Meet all present and future national and international statutory requirements.
- 2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

TEMIC Semiconductor GmbH has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

- 1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively
- 2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA
- 3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

TEMIC Semiconductor GmbH can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

We reserve the right to make changes to improve technical design and may do so without further notice. Parameters can vary in different applications. All operating parameters must be validated for each customer application by the customer. Should the buyer use TEMIC products for any unintended or unauthorized application, the buyer shall indemnify TEMIC against all claims, costs, damages, and expenses, arising out of, directly or indirectly, any claim of personal damage, injury or death associated with such unintended or unauthorized use.

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